

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicant(s) : Hachikian
Serial No. : 10/778,008
Filed : February 12, 2004
Title : INFILTRANT SYSTEM FOR RAPID PROTOTYPING
PROCESS
Docket No. : ITW 0009 PA /41038.13/1455
Examiner : M. Feely
Art Unit : 1796
Confirmation No. : 3347

DECLARATION OF ZAKAR R. HACHIKIAN

Zakar R. Hachikian, the applicant in the above-identified patent application, declares as follows:

1. I am the inventor of claims 1-61 of the above-identified patent application and inventor of the subject matter described and claimed therein. I am an employee of Illinois Tool Works, Inc. (ITW), assignee of the present invention.
2. Amides and imidazolines are two different groups of epoxy curing agents. Imidazolines are generally added to amides to give better adhesion to substrates; however, not all amide epoxy curing agents contain imidazolines. Thus, an epoxy curing agent from an amide may or may not contain imidazoline.
3. One of skill in the art would understand the term amide/imidazoline as meaning combinations of amides and imidazolines.
4. The viscosity of adhesive component is frequently provided without specifying the temperature at which the viscosity was measured. For example, the general information concerning Lord® Acrylic Adhesives and Accelerators available from Lord

Serial No. 10/778.008

Docket No. ITW 0009 PA/41038.13/1455

Corp. provides typical viscosities for various products without identifying the temperature at which it was measured. The Technical Data Sheets do include the temperature for the viscosity data. See Exhibits A and B. The Technical Data Sheets for several Loctite® Hysol® epoxy adhesives available from Henkel Corp. include the viscosity data, but not the temperature at which the viscosity was measured. See Exhibit C.

5. When viscosity data is provided without specifying the temperature at which it was measured, one of skill in the art would understand it to be measured at room temperature.

The declarant further states that the above statements were made with the knowledge that willful false statements and the like are punishable by fine and/or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of this application or any patent resulting therefrom.

Date: 10/31/08


Zakar R. Hachikian